

FFM101-MS THRU FFM107-MS

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FFM101-MS THRU FFM107-MS

1.0A Surface Mount Fast Recovery Rectifiers 50V-1000V

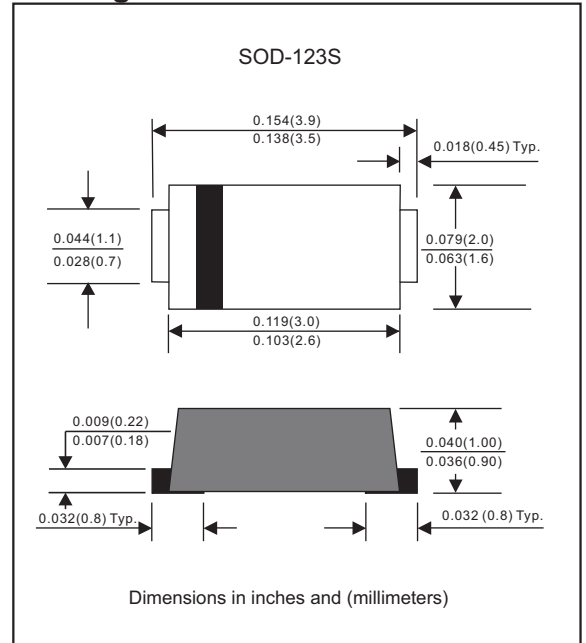
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance
- Low profile surface mounted application in order to optimize board space
- Tiny plastic SMD package
- High current capability
- Fast switching for high efficiency
- High surge current capability
- Glass passivated chip junction
- Lead-free parts meet RoHS requirements
- Suffix "-H" indicates Halogen-free parts, ex. FFM101-MS-H

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123S/MINI SMA
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.0155 gram

Package outline



Maximum ratings (AT T_A=25°C unless otherwise noted)

| PARAMETER | SYMBOLS | FFM101-MS | FFM102-MS | FFM103-MS | FFM104-MS | FFM105-MS | FFM106-MS | FFM107-MS | UNIT |
|--|------------------|-------------|-----------|-----------|-----------|-----------|-----------|-----------|------|
| Maximum repetitive peak reverse voltage | V _{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V _{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum continuous reverse voltage | V _R | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum average forward rectified current | I _O | 1.0 | | | | | | | A |
| Non-repetitive peak forward surge current 8.3ms single half sine-wave | I _{FSM} | 30 | | | | | | | A |
| Typical junction capacitance (Note 1) | C _J | 15 | | | | | | | pF |
| Operating junction temperature range | T _J | -55 to +150 | | | | | | | °C |
| Storage temperature range | T _{STG} | -65 to +175 | | | | | | | °C |

Electrical characteristics (AT T_A=25°C unless otherwise noted)

| PARAMETER | SYMBOLS | FFM101-MS | FFM102-MS | FFM103-MS | FFM104-MS | FFM105-MS | FFM106-MS | FFM107-MS | UNIT |
|---|-----------------|------------|-----------|-----------|-----------|-----------|-----------|-----------|----------|
| Maximum instantaneous forward voltage at I _F =1.0A | V _F | 1.3 | | | | | | | V |
| Maximum reverse leakage current T _J =25°C at rated V _R T _J =125°C | I _R | 5.0 100 | | | | | | | μA μA |
| Maximum reverse recovery time (Note 2) | t _{rr} | 150 | | | | 250 | 500 | | ns |

Thermal characteristics

| PARAMETER | SYMBOLS | FFM101-MS | FFM102-MS | FFM103-MS | FFM104-MS | FFM105-MS | FFM106-MS | FFM107-MS | UNIT |
|---|------------------|-----------|-----------|-----------|-----------|-----------|-----------|-----------|------|
| Typical thermal resistance junction to ambient (Note 3) | R _{θJA} | 72 | | | | | | | °C/W |
| Typical thermal resistance junction to case (Note 3) | R _{θJC} | 52 | | | | | | | °C/W |

Notes 1: Measured at 1 MHz and applied reverse voltage of 4.0 VDC
 2: Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A
 3: Mounted on FR-4 PCB Copper, minimum recommended pad layout

Rating and characteristic curves (FFM101-MS THRU FFM107-MS)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

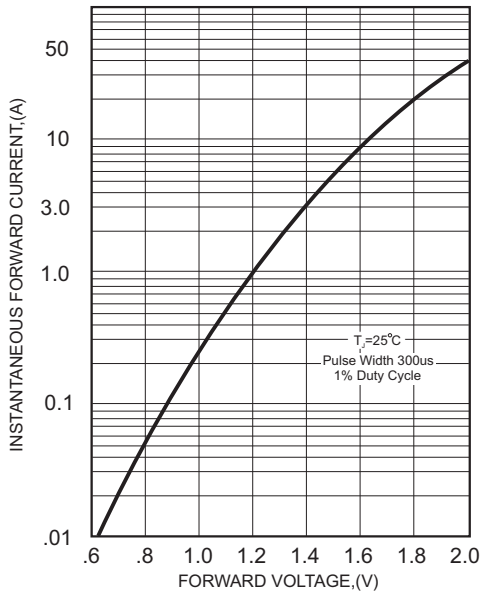


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

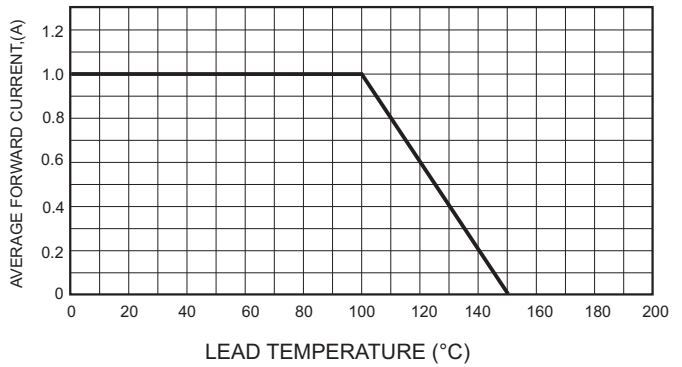


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

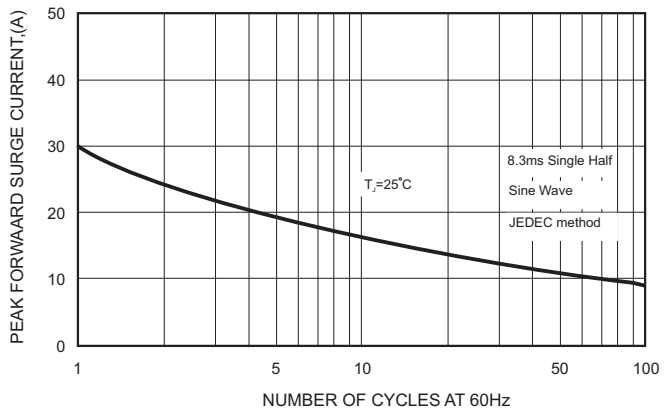


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS

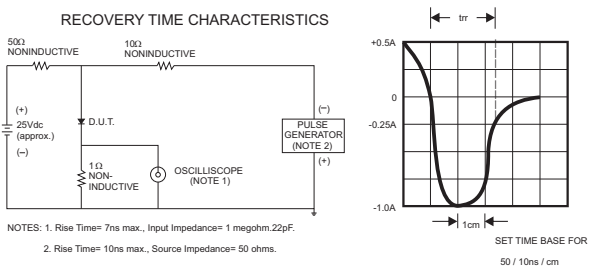


FIG.6 - TYPICAL REVERSE CHARACTERISTICS

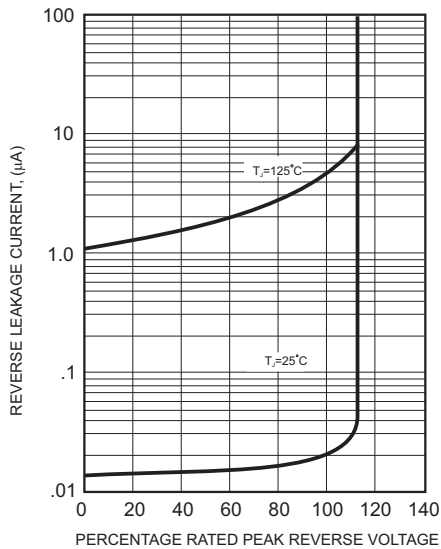
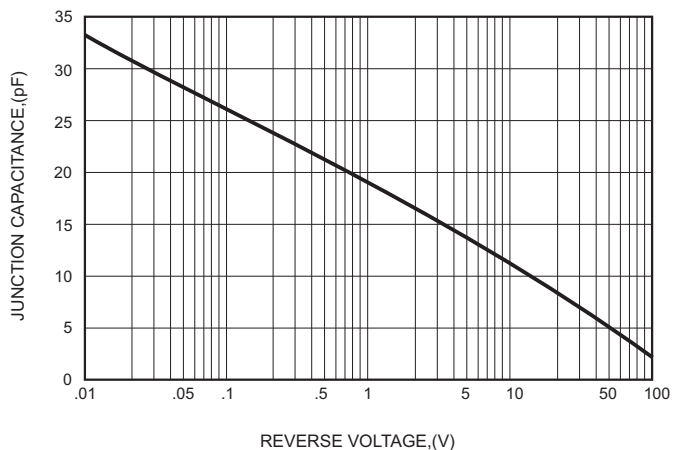




FIG.5-TYPICAL JUNCTION CAPACITANCE



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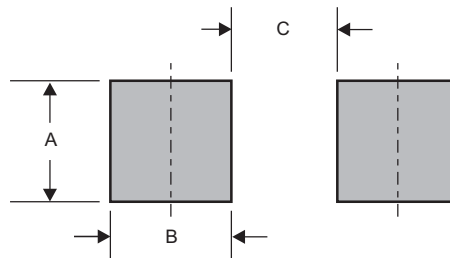
Pinning information

| Pin | Simplified outline | Symbol |
|----------------------------|---|---|
| Pin1 cathode Pin2 anode |  |  |

Marking

| Type number | Marking code |
|-------------|--------------|
| FFM101-MS | F1 |
| FFM102-MS | F2 |
| FFM103-MS | F3 |
| FFM104-MS | F4 |
| FFM105-MS | F5 |
| FFM106-MS | F6 |
| FFM107-MS | F7 |

Suggested solder pad layout

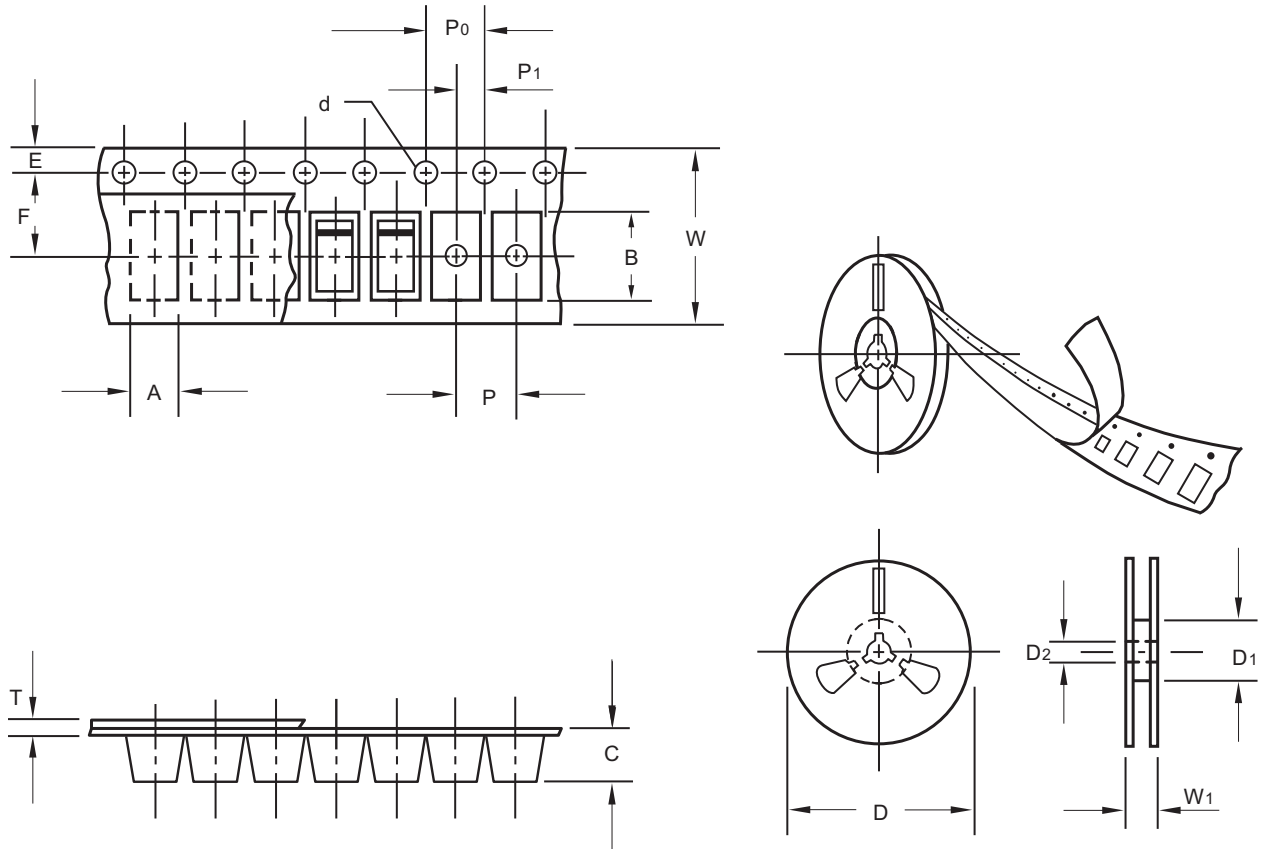


Dimensions in inches and (millimeters)

| PACKAGE | A | B | C |
|----------|--------------|--------------|--------------|
| SOD-123S | 0.044 (1.10) | 0.040 (1.00) | 0.079 (2.00) |

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Packing information



unit:mm

| Item | Symbol | Tolerance | SOD-123S |
|---------------------------|--------|-----------|----------|
| Carrier width | A | 0.1 | 2.00 |
| Carrier length | B | 0.1 | 3.85 |
| Carrier depth | C | 0.1 | 1.10 |
| Sprocket hole | d | 0.1 | 1.50 |
| 13" Reel outside diameter | D | 2.0 | - |
| 13" Reel inner diameter | D1 | min | - |
| 7" Reel outside diameter | D | 2.0 | 178.00 |
| 7" Reel inner diameter | D1 | min | 62.00 |
| Feed hole diameter | D2 | 0.5 | 13.00 |
| Sprocket hole position | E | 0.1 | 1.75 |
| Punch hole position | F | 0.1 | 3.50 |
| Punch hole pitch | P | 0.1 | 4.00 |
| Sprocket hole pitch | P0 | 0.1 | 4.00 |
| Embossment center | P1 | 0.1 | 2.00 |
| Overall tape thickness | T | 0.1 | 0.23 |
| Tape width | W | 0.3 | 8.00 |
| Reel width | W1 | 1.0 | 11.40 |

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

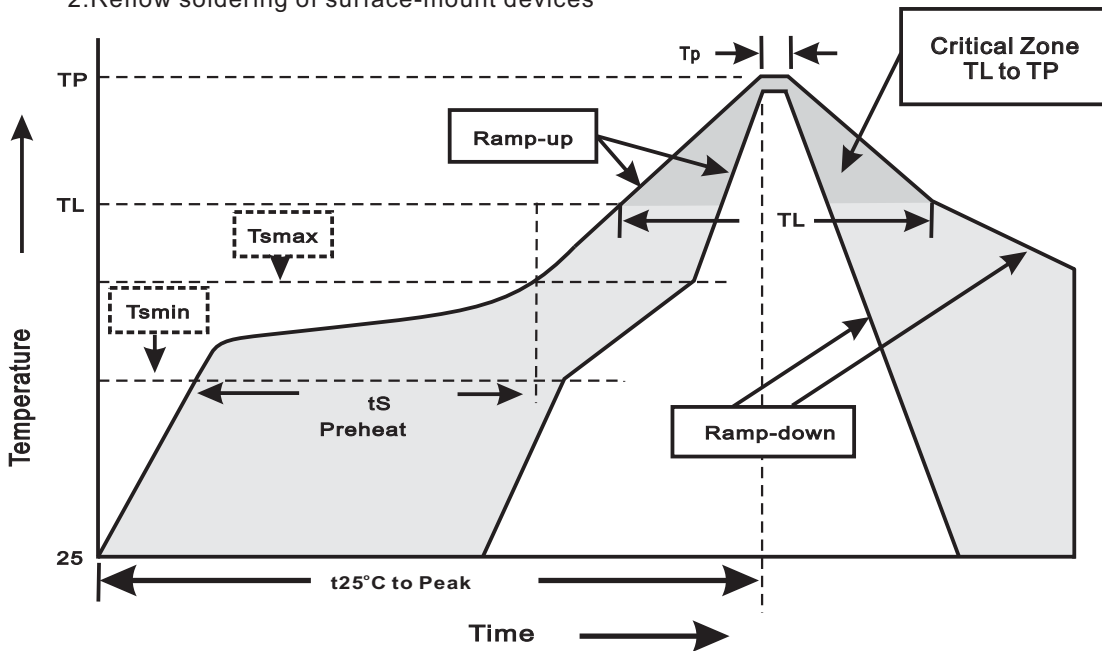
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Reel packing

| PACKAGE | REEL SIZE | REEL (pcs) | COMPONENT SPACING (m/m) | BOX (pcs) | INNER BOX (m/m) | REEL DIA, (m/m) | CARTON SIZE (m/m) | CARTON (pcs) | APPROX. GROSS WEIGHT (kg) |
|----------|-----------|------------|-------------------------|-----------|-----------------|-----------------|-------------------|--------------|---------------------------|
| SOD-123S | 7" | 3,000 | 4.0 | 30,000 | 183*123*183 | 178 | 382*257*387 | 240,000 | 9.5 |

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

| Profile Feature | Soldering Condition |
|--|-----------------------------|
| Average ramp-up rate(TL to TP) | <3°C/sec |
| Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts) | 150°C 200°C 60~120sec |
| Tsmax to TL -Ramp-upRate | <3°C/sec |
| Time maintained above: -Temperature(TL) -Time(tL) | 217°C 60~260sec |
| Peak Temperature(TP) | 255°C-0/+5°C |
| Time within 5°C of actual Peak Temperature(tp) | 10~30sec |
| Ramp-down Rate | <6°C/sec |
| Time 25°C to Peak Temperature | <6minutes |

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High reliability test capabilities

| Item Test | Conditions | Reference |
|-----------------------------------|--|-------------------------------|
| 1. Solder Resistance | at 260±5°C for 10±2sec. | MIL-STD-750D METHOD-2031 |
| 2. Solderability | at 245±5°C for 5 sec. | MIL-STD-202F METHOD-208 |
| 3. High Temperature Reverse Bias | $V_R=80\%$ rate at $T_J=150^\circ\text{C}$ for 168 hrs. | MIL-STD-750D METHOD-1038 |
| 4. Forward Operation Life | Rated average rectifier current at $T_A=25^\circ\text{C}$ for 500hrs. | MIL-STD-750D METHOD-1027 |
| 5. Intermittent Operation Life | $T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles. | MIL-STD-750D METHOD-1036 |
| 6. Pressure Cooker | 15P _{SIG} at $T_A=121^\circ\text{C}$ for 4 hrs. | JESD22-A102 |
| 7. Temperature Cycling | -55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles. | MIL-STD-750D METHOD-1051 |
| 8. Forward Surge | 8.3ms single half sine-wave , one surge. | MIL-STD-750D METHOD-4066-2 |
| 9. Humidity | at $T_A=85^\circ\text{C}$, RH=85% for 1000hrs. | MIL-STD-750D METHOD-1021 |
| 10. High Temperature Storage Life | at 175°C for 1000 hrs. | MIL-STD-750D METHOD-1031 |